onsemi  Contact Name  Title - Contact  Phone - Contact*  Email - Contact*  Product-Env-Stewards  Product-Enviro Compliance  NA  Product-Env-Stewards@onsemi.c  Authorized Representative*  Title - Representative  Phone - Representative*  Email - Representative*	IPC SSOCIATION CONNECTION LECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name* Company unique ID Unique ID Authority Response Date* 2025-05-11 Contact Name Title - Contact Product Enviro Compliance Unique ID Authority Response Date* 2025-05-11 Contact Name Product Enviro Compliance NA Product Enviro Stewards © onsemic NA	52-21.1						e *					rials and Mfg Information			
nsemi ontact Name Title - Contact Phone - Contact* Phone - Contact* Product-Env-Stewards Prod	ıpplier Inforr	mation													
Title - Contact Name Product Env-Stewards Product Env-Stewards Product Enviro Compliance Phone - Representative* Product-Env-Stewards Product Enviro Compliance Phone - Representative* Product-Env-Stewards Product Enviro Compliance Phone - Representative* Product-Env-Stewards Produ	Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
Product-Env-Stewards uthorized Representative* Title - Representative Product-Env-Stewards Pr	onsemi											2025-05-11			
Authorized Representative* Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM  FFSH2065ADN-F155 650V 20A SIC SBD  2025-05-11 CPA 5456.925 mg  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy Matte Tin (Sn) - annealed CU Alloy NA  Product-Env-Stewards@onsemi.ce Weight* UOM  Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cy Namber	Contact Name			Title - Contact			1	Phone - Contact*			Email	Email - Contact*			
Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM  FFSH2065ADN-F155 650V 20A SIC SBD 2025-05-11 CPA 5456.925 mg  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy Matte Tin (Sn) - annealed CU Alloy NA  Product-Env-Stewards@onsemi.c  Weight* UOM  Product-Env-Stewards@onsemi.c  Weight* UOM  Product-Env-Stewards@onsemi.c  Weight* UOM  Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cy  Na  O C 30 Seconds 3	Product-Env-Stewards			Product Enviro Compliance				NA			Prod	Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative*			Title - Representative			1	Phone - Representative*			Email	Email - Representative*			
FFSH2065ADN-F155 650V 20A SIC SBD 2025-05-11 CPA 5456.925 mg    Internation   CPA	Product-Env-Stewards			Product Enviro Compliance				NA			Prod	Product-Env-Stewards@onsemi.com			
Terminal Plating / Grid Array Material   Terminal Base Alloy   J-STD-020 MSL Rating   Peak Process Body Temperature   Max Time at Peak Temperature   Number of Reflow Cy	Request	Requester Item Number		Mfr Item Number Mfr Item Name			E		Version	Manufacturing Site		Weight*	UOM	Unit Type	
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cy Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3			FFSH2065ADN-F155 650V 20A SIC SBD		BD		2025-05-11		СРА		5456.925	mg	Each		
Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3				ID	.,,	( GTD 020 MG	T. D. C	D 1 D	D 1 T	M Ti	D 1 T		CD CL		
Patter III (bi) dimensed to the seconds b	8					L Rating				1.		er of Reflow Cyc	cles		
omments		in (Sn) - annealed	(	LU Alloy		NA		U	IC.	30	sec	conds   3			
	mments														
or more information regarding material composition please refer to page 3			•,•	1 6 :											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Ilability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	32.0	mg	Supplier	Silicon Carbide	409-21-2		32	mg
Die Attach Solder	35.025	mg	Supplier	Silver (Ag)	7440-22-4		0.8756	mg
			A	Lead (Pb)	7439-92-1	7a	32.3981	mg
			Supplier	Tin (Sn)	7440-31-5		1.7512	mg
Lead Frame	3612.9	mg	В	Nickel (Ni)	7440-02-0		1.8065	mg
			Supplier	Iron (Fe)	7439-89-6		3.6129	mg
			Supplier	Copper (Cu)	7440-50-8		3606.3967	mg
			Supplier	Phosphorus (P)	7723-14-0		1.0836	mg
Mold Compound-Black	1740.0		Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		87	mg
			Supplier	Proprietary	Proprietary Data		87	mg
			Supplier	Carbon Black (C)	1333-86-4		8.7	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		78.3	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1305	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		87	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		87	mg
Plating	31.0	mg	Supplier	Tin (Sn)	7440-31-5		31	mg
Wire Bond - Al	6.0	mg	Supplier	Aluminum (Al)	7429-90-5		6	mg